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Poster Presentation

## [FMCp3]Metrology &Manufacturing

Thu. Nov 28, 2019 10:40 AM - 1:10 PM Main Hall (1F)

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### [FMCp3-5]Post-oven Induced Surface Hydrophobicity Degradation of CF<sub>4</sub> Plasma Treated Polyimide Photo Resistance

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Keywords:polyimide film, hydrophobicity, plasma treatment, bank, post-oven

Polyimide films were treated by CF<sub>4</sub> plasma to serve as bank material for inkjet printing OLED. Excellent hydrophobicity was thus obtained due to the F implantation. However, degradation of hydrophobicity was observed by post-oven, an inevitable process for inkjet printing. This degradation is probably caused by the H<sub>2</sub>O/O<sub>2</sub> chemical adsorption.